IEEE P802.3df 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet Task Force

Approved Meeting Minutes, prepared by John D'Ambrosia, Mark Nowell, and Kent Lusted

14 Sept 2022
Interim Teleconference Meeting
IEEE P802.3df Task Force 14 Sept 2022 Meeting Task Force Page -
https://www.ieee802.org/3/df/public/22_09/index.html

Session called to order at 9:00 am ET (all times ET), 14 Sept 2022
Meeting called to order by John D'Ambrosia, IEEE P802.3df Task Force Chair

Presentation #1	**Agenda and General Information**
Presenters	John D'Ambrosia
URL	https://www.ieee802.org/3/df/public/22_09/agenda_3df_b_2209.pdf

Chair welcomed everyone to the meeting.

Chair reviewed the agenda (Slide #2) and noted presentation order on Slide #3. Chair noted that individuals should check the webpage for the latest version of each presentation. Chair noted that the presentation times are subject to change.

Chair asked if there were any objections to the agenda, and there were none. Chair noted that the title of slide #2 shows "July 2022" but the agenda was for the September 2022 interim meeting. The agenda was considered approved by unanimous consent.

Chair reminded participants to sign into the IEEE Meeting Attendance Tool.

Minutes –
- July 2022 Plenary – https://www.ieee802.org/3/df/public/22_07/minutes_3df_2207_unapproved.pdf

Chair asked if there were any other corrections or modifications. There were none. Chair if there were any objections to approving the posted minutes. There were none, and the minutes were considered approved by unanimous consent.

Chair reviewed meeting decorum. (See Slide #4.) Chair asked if there were any members of the press present. No one responded.
Chair reviewed attendance. (See Slide #5.)
Chair reviewed the Task Force Project Information / Organization. (See Slides #6).
Chair reviewed ground rules. (See Slide #7.)
Chair reviewed the current state of the Task Force. (See Slide #8.)
Chair reviewed voting in the task force. (See Slide #9.)

Slide #17 - Chair noted that the information regarding the IEEE SA Policies had been sent out via the Task Force reflector (see: https://www.ieee802.org/3/B400G/email/msg00380.html), and requested that individuals review the following IEEE SA policies prior to the interim meeting –
- IEEE SA Patent policy
- IEEE SA Copyright Policy
- IEEE SA Participation Policy

Chair asked if anyone needed to review the policies at that time – there were no requests to do so from in-person nor remote attendees.

Chair presented the third slide (See Slide #31) of the IEEE SA Patent Policy slides. Chair did call for Potentially Essential Patents, and no one came forward.

Chair presented the second slide (See Slide #36) of the IEEE SA Copyright Policy slides. Chair noted – "By participating in this activity, you agree to comply with the IEEE Code of Ethics, all applicable laws, and all IEEE policies and procedures including, but not limited to, the IEEE SA Copyright Policy."

Chair presented the second slide (See Slide #40) of the IEEE SA Participation Policy slides. Chair noted – "Participants in the IEEE-SA "individual process" shall act independently of others, including employers. By participating in standards activities using the "individual process", you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation."

Chair reviewed status of Architecture & Logic, Electrical, and Optics ad hocs. See Slides #12-13.

Chair noted there was one liaison from the OIF for the Task Force to consider (see: Slide #11, https://www.ieee802.org/3/df/public/22_09/OIF_liaison_letter_IEEE803.2_800LR_29Aug22_Redacted.pdf). Chair noted that the liaison would be considered during the November session. Chair would prepare a draft liaison communication for the Task Force to consider and post it on the website.

At 9:17 a.m., John D'Ambrosia passed the meeting Chair responsibilities to Mark Nowell.

Presentation #2	**Proposed Project Documentation Packages**
Presenters	John D'Ambrosia
URL	https://www.ieee802.org/3/df/public/22_09/dambrosia_3df_01b_2209.pdf

Author noted that some files listed on slide 3 had updated revisions and the updated files could be found on the Task Force website. (see: https://www.ieee802.org/3/df/public/22_09/index.html) Questions of clarification were addressed and discussed.

Presentations #3-8 & URLs	**IEEE P802.3df Documentation Package** • Proposed Objectives - Modified P802.3df PAR (URL: https://www.ieee802.org/3/df/public/22_09/dambrosia_3df_02_2209.pdf) • Proposed Draft IEEE P802.3df PAR Modification Responses 400 GbE and 800 GbE Objectives (URL: https://www.ieee802.org/3/df/public/22_09/dambrosia_3df_03a_2209.pdf) • Proposed Draft IEEE P802.3df CSD Modification Responses 400 GbE and 800 GbE Objectives (URL: https://www.ieee802.org/3/df/public/22_09/dambrosia_3df_04a_2209.pdf) **IEEE P802.3dj Documentation Package** • Proposed Objectives – P802.3dj PAR (URL: https://www.ieee802.org/3/df/public/22_09/dambrosia_3df_05_2209.pdf) • Proposed Draft IEEE P802.3dj PAR Responses 200 GbE, 400 GbE, 800 GbE and 1.6 TbE Objectives (URL: https://www.ieee802.org/3/df/public/22_09/dambrosia_3df_06_2209.pdf) • Proposed Draft IEEE P802.3dj CSD Responses 200 GbE, 400 GbE, 800 GbE, and 1.6 TbE Objectives (URL: https://www.ieee802.org/3/df/public/22_09/dambrosia_3df_07a_2209.pdf)
Presenters	John D'Ambrosia

The noted documentation packages were reviewed with the Task Force. Author noted that some files listed in presentations #3-#8 had updated revisions and the updated files could be found on the Task Force website. (see: https://www.ieee802.org/3/df/public/22_09/index.html)

There were updates made to the PAR item 5.2B on slide 22 of the "Proposed Draft IEEE P802.3dj PAR Responses 200 GbE, 400 GbE, 800 GbE and 1.6 TbE Objectives" and saved as version '06a'. (see: https://www.ieee802.org/3/df/public/22_09/dambrosia_3df_06a_2209.pdf).

There were updates made to the CSD item Distinct Item on slide 17 and CSD item Economic Feasibility on slide 19 of "Proposed Draft IEEE P802.3dj CSD Responses 200 GbE, 400 GbE, 800 GbE, and 1.6 TbE Objectives" and saved as version '07b'. (see: https://www.ieee802.org/3/df/public/22_09/dambrosia_3df_07b_2209.pdf)

At 10:38 am, Mark Nowell passed meeting chair responsibilities back to John D'Ambrosia

Motion #1

Move that the IEEE P802.3df Task Force develop:

- A modification of the IEEE P802.3df PAR to address "Media Access Control Parameters for 800 Gb/s and Physical Layers and Management Parameters for 400 Gb/s and 800 Gb/s Operation"
- A new IEEE P802.3dj PAR to address "Media Access Control Parameters for 1.6 Tb/s and, Physical Layers and Management Parameters for 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Operation."

M: Mark Nowell
S: Jim Weaver
Technical 802.3 voters (>=75%)
Result: passed by unanimous consent 10:42 a.m.

Motion #2

Move to adopt:

- The objectives stated on Slide #6 of dambrosia_3df_02_2209 for the modified IEEE P802.3df Project
- The objectives stated on Slides #6 – 7 of dambrosia_3df_05_2209 for the IEEE P802.3dj Project

M: Ali Ghiasi
S: Mark Nowell
Technical 802.3 voters (>=75%)
Result: passed by unanimous consent 10:46 a.m.

Chair discussed the next steps with the project documentation approval process.

Chair noted that he plans for the 3df Task Force to meet during the IEEE 802.3 Plenary meeting to address feedback received on the documentation packages. If the changes are approved, the first meeting for the P802.3dj Task Force could be in January 2023.

Break at 10:50 a.m. Resumed at 10:55 a.m.

Presentation #9	Link Training baseline for eight-lane PMDs
Presenters	Kent Lusted
URL	https://www.ieee802.org/3/df/public/22_09/lusted_3df_01a_2209.pdf

Questions of clarification were addressed and discussed.

Straw Poll #1:

For the 800GBASE-CR8 and 800GBASE-KR8 link training baseline, I would support part A proposed in lusted_3df_01a_2209 slides 6-11.
Results: Chair asked if there was anyone that would vote in objection. There was an objection. Chair then used the online polling function to perform the straw poll.
Results: Y: 49 , N: 2 , A: 16

Motion #3

Move to adopt the link training baseline for 800GBASE-CR8 and 800GBASE-KR8 PMDs in lusted_3df_01a_220914 slides 6-11
M: Kent Lusted
S: Adee Ran
Technical 802.3 voters (>=75%)
Result:

Motion #4:

Move to table Motion #3
M: Piers Dawe
S:
Procedural (>50%)
Result: Motion fails due to lack of a second

Motion #3

Move to adopt the link training baseline for 800GBASE-CR8 and 800GBASE-KR8 PMDs in lusted_3df_01a_220914 slides 6-11
M: Kent Lusted
S: Adee Ran
Technical 802.3 voters (>=75%)
Result: passed by unanimous consent 11:34 a.m.

Chair reviewed future meetings. See Slide #14. Chair reminded participants of the early reservation deadlines for the November 2022 Plenary meeting and the hotel. Registration for the November 2022 Plenary meeting is required for all attendees.

Chair noted that the leadership would be discussing the project schedule and would provide updates.

Kent Lusted, IEEE P802.3df electrical track chair, reminded participants of the electrical ad hoc scheduled for 21 September 2022. The meeting details were available on the IEEE Call and Meeting calendar. (see: https://www.ieee802.org/3/calendar.html)

Meeting adjourned at 11:45 am.

Attendees (Per IMAT Report)

Abbott, John	Corning Incorporated	Corning Incorporated
Aekins, Rob	Legrand	Legrand
Akbaba, Enis	Analog Devices Inc.	Analog Devices Inc.
Ben-Artsi, Liav	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Bernier, Eric		Huawei Technologies Canada; Huawei Technologies Co., Ltd
Bliss, William	Broadcom Corporation	Broadcom Corporation
Bois, Karl	NVIDIA Corporation	NVIDIA Corporation
Borda, jamila josip	BMW Group	BMW Group
Bovington, Jock		Cisco Systems, Inc.
Brillhart, Theodore	Fluke Corporation	Fluke Corporation
Brooks, Paul	Viavi solutions GmbH	Viavi Solutions
Brown, Matthew	Huawei Technologies Canada	Huawei Technologies Canada
Bruckman, Leon	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Cai, Yuefeng		Huawei Technologies Co., Ltd
Calvin, John	Keysight Technologies	Keysight Technologies
Carlson, Steven	High-Speed Design Inc.	HSD, Robert Bosch GmbH, Ethernovia
Cassan, Dave	Alphawave	Alphawave
Chang, Yongmao	Inphi Corporation	Source Photonics
cheng, weiqiang	China Mobile Limited	China Mobile Limited
D'Ambrosia, John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Subsidiary of Huawei
Dawe, Piers J G	NVIDIA	Nvidia
de Koos, Andras	Microchip Technology Inc	Microchip Technology, Inc.
Deandrea, John	Finisar Corporation	Finisar Corporation
Del Vecchio, Peter		Broadcom Corporation
Diminico, Christopher	M C Communications, LLC	Panduit Corp.
Donahue, Curtis	Rohde & Schwarz	Rohde & Schwarz
Dube, Kathryn	UNH-IOL	UNH-IOL
Dudek, Michael	Marvell	Marvell
Dumais, Patrick		Huawei Technologies Co., Ltd
Effenberger, Frank	Futurewei Technologies	Futurewei Technologies
Estes, David	Spirent Communications	Spirent Communications
Ewen, John	Marvell	Marvell
Feyh, German	Broadcom Corporation	Broadcom Corporation
Gao, Xiangrong	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.
Gore, Brandon	Samtec, Inc.	Samtec, Inc.
Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
Graba, James	Broadcom Corporation	Broadcom Corporation

Gustlin, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Healey, Adam	Broadcom Inc.	Broadcom Inc.
Heck, Howard	Intel	Intel
Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor
Huang, Kechao	Huawei Technologies Co., Ltd.	Huawei Technologies Co., Ltd.
HUANG, QINHUI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Huber, Thomas	Nokia	Nokia
Ingham, Jonathan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Isono, Hideki	Fujitsu Optical Components Limited	Fujitsu Optical Components Limited
Issenhuth, Tom	Issenhuth Consulting, LLC	Huawei Technologies Co., Ltd
Jackson, Kenneth	Sumitomo Electric Device Innovations, USA	Sumitomo Electric Industries, LTD
Jiang, Chendi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Johnson, John	Broadcom Corporation	Broadcom Corporation
Kabra, Lokesh	Synopsys, Inc.	Synopsys, Inc.
Kao, Chienping	Intel	Intel
Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.
Kim, Kihong/Joshua	Hirose Electric (USA), Inc.	Hirose Electric (USA), Inc.
Kim, Yongbum	Tenstorrent	Tenstorrent
Kimber, Eric	Semtech Ltd	Semtech Ltd
Klempa, Michael	Amphenol Corporation	Alphawave IP
Klingensmith, William	U.S. Federal Government	DoD
Kochuparambil, Elizabeth	Cisco Systems, Inc.	Cisco Systems, Inc.
Kocsis, Sam	Amphenol Corporation	Amphenol Corporation
Koehler, Daniel	MorethanIP	Synopsys, Inc.
Koeppendoerfer, Erwin	LEONI Kabel GmbH	LEONI
Kondo, Taiji	MegaChips Corporation	Dexerials Corporation
Lee, Sylvanus	Leviton Manufacturing Co.	Leviton Manufacturing Co.
Lewis, David	Lumentum Inc.	Lumentum Inc.
li, huanlu		Huawei Technologies Co., Ltd
Li, Mike-Peng	Intel	Intel
Li, Pei-Rong	MediaTek Inc.	MediaTek Inc.
Lieder, Eyal		Marvell Semiconductor, Inc.
Lim, Jane	Cisco Systems, Inc.	Cisco Systems, Inc.
Liu, Cathy	Broadcom Corporation	Broadcom Corporation
Liu, Hai-Feng	HG Genuine	HG Genuine
Lu, Yuchun	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Lusted, Kent	Intel	Intel
Mak, Gary	Marvell Corporation	Marvell Semiconductor, Inc.
Maki, Jeffery	Juniper Networks, Inc.	Juniper Networks, Inc.
Malicoat, David	Malicoat Networking Solutions	Malicoat Networking Solutions; SENKO Advanced Components
Maniloff, Eric	Ciena Corporation	Ciena Corporation
McMillan, Larry	Western Digital Corporation	Western Digital Corporation
Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
mi, guangcan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd

Moorwood, Charles	Keysight Technologies	Keysight Technologies
Mueller, Thomas	Rosenberger	Rosenberger
Muller, Shimon	Enfabrica Corp.	Enfabrica Corp.
Nakamoto, Edward	Spirent Communications	Spirent Communications
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.
Nicholl, Shawn	Xilinx	Advanced Micro Devices (AMD)
Ninomiya, Takuya		Senko Advanced Components
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Ofelt, David	Juniper Networks, Inc.	Juniper Networks, Inc.
Omori, Kumi	NEC Corporation	NEC Corporation
Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
Palkert, Thomas	Macom, Samtec	Samtec-Macom
Pandey, Sujan	Huawei Technologies (Netherlands) B.V.	Huawei Technologies (Netherlands) B.V.
PARK, CHUL SOO	Juniper Networks Inc.	Juniper Networks, Inc.
Parkholm, Ulf	Telefon AB LM Ericsson	Telefon AB LM Ericsson
Parsons, Earl	CommScope, Inc.	CommScope, Inc.
peng, semmy		Huawei Technologies Co., Ltd
Pepper, Gerald	Keysight Technologies	Keysight Technologies
Piehler, David	Dell Technologies	Dell
Pimpinella, Rick	Panduit Corp.	Panduit Corp.
Quan, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rabinovich, Rick	Keysight Technologies	Keysight Technologies
Radhamohan, Rajeshmohan	Cisco Systems, Inc.	Cisco Systems, Inc.
Rahn, Jeffrey	Facebook	Facebook
Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.
Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rodes, Roberto	II-VI	II-VI
Sakai, Toshiaki	Socionext Inc.	socionext
Sambasivan, Sam	AT&T	AT&T
Savi, Olindo	Hubbell Incorporated	Hubbell Incorporated
She, Qingya	Fujitsu Network Communications	Fujitsu Network Communications
Shrikhande, Kapil	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Shukla, Priyank	Synopsys, Inc.	Synopsys, Inc.
SIDHIQUE, ABOOBACKKAR		Indian Institute of Technology Bombay
Sikkink, Mark		Hewlett Packard Enterprise
Simms, William	NVIDIA Corporation	NVIDIA Corporation
Slavick, Jeff	Broadcom Inc	Broadcom Inc
Sluyski, MIke		Cisco Systems, Inc.
Sommers, Scott	Molex LLC	Molex Incorporated
Son, Yung Sung	Optomind Inc	Optomind Inc
Sorbara, Massimo	GLOBALFOUNDRIES	GLOBALFOUNDIRES
Souvignier, Tom	Broadcom Corporation	Broadcom Corporation
Sprague, Edward	Infinera Corporation	Infinera Corporation
Stassar, Peter	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
SU, CHANGZHENG		Huawei Technologies Co., Ltd
Summers, Robert		Broadcom Corporation

Sun, Junqing	Credo Semiconductor	Credo Semiconductor
Sun, Yi		OFS
TAKAHARA, TOMOO	FUJITSU LABORATORIES LIMITED	FUJITSU LIMITED
Terada, Masaru	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC
Theodoras, James	HG Genuine	HG Genuine
Tooyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.
Tracy, Nathan	TE Connectivity	TE Connectivity
Tran, Viet	Keysight Technologies	Keysight Technologies
Ulrichs, Ed	Intel	Intel
Wang, Haojie	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)
Wang, Ruoxu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Weaver, James	Arista Networks	Arista Networks
Welch, Brian	Cisco Systems, Inc.	Luxtera
Wu, Mau-Lin	MediaTek Inc.	MediaTek Inc.
yan, zengchao		Huawei Technologies Co., Ltd
Yin, Shuang		Google
Zhang, Tingting		Huawei Technologies Co., Ltd
Zhong, Qiwen	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zhuang, Yan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd